INDIAN INSTITUTE OF TECHNOLOGY BOMBAY
MATERIALS MANAGEMENT DIVISION
Powai, Mumbai 400076

PR No. 1000019200 (Rfx No. 6100000793)

Detailed Technical Specifications for Wire Bonder

1. The wire bonder should have provision for thermosonic Wedge-Wedge, Ball-Wedge, Ribbon and Bump bonding
2. The bonder should be able to use Gold and Aluminum wires of diameter 25 µm or smaller to 75 µm or larger.
3. The Z Axis movement, as well as the clamp movement should be motorized, with additional manual control of Z motion. The Z movement should be 15 mm or more and the Y movement should be 10 mm or more.
4. The work stage surface should have a minimum diameter of 90 mm.
5. The work stage temperature should be variable between room temperature and minimum 250 °C.
6. The bonder unit should be provided with dual illumination, touch screen control panel, video camera, HDMI and SD-card
7. At least two wedge tools for 25µ Au wedge bonding should be included in the quote.
8. At least two capillary tools for 25µ Au ball bonding should be included in the quote
9. Two 100 m spools of 25µ Gold wire should be included in the quote.
10. At least two wedge tools for 25µm Aluminum wire wedge bonding should be included in the quote.
11. Two 100m spools of 25µm Aluminum wire should be included in the quote
12. Tool box (usually consisting of 2 tweezers, allen keys, hook, 1 substrate, 3 Cu-screws, 1 glass, 1 torque wrench) to be provided with the wire bonder
13. The product should have a minimum warranty of one year.
14. Technical support should be available within India
15. The manufacturer should provide a list of at least 3 users, the list consisting of at least one Indian user, who will be willing to provide her/his/their feedback on the reliability of the equipment and the technical support.